Preferred Device

Transient Voltage Suppressor Diode

SOD-323 Zeners for ESD Protection

These Zener diodes are designed for applications requiring transient overvoltage protection capability. They are intended for use in voltage and ESD sensitive equipment such as computers, printers, business machines, communication systems, medical equipment and other applications. These devices are ideal for situations where board space is at a premium.

Specification Features:

- Steady State Power Routing of 200 mW
- Peak Power 350 W (8 \times 20 μ s)
- Low Leakage
- Cathode Indicated by Polarity Band
- Package Weight: 4.507 mg/wmt
- Meets IEC61000-4-2 Level 4, 15 kV (Air), 8 kV (Contact)
- Meets IEC6100-4-4 Level 4, 40 A
- Meets IEC6100-4-5 (Lightning), 24 A
- Meets 16 kV Human Body Model ESD Requirements
- Pb-Free Packages are Available

Mechanical Characteristics:

CASE: Void-free, transfer-molded, thermosetting plastic

Epoxy Meets UL 94, V-0

LEAD FINISH: 100% Matte Sn (Tin)

MOUNTING POSITION: Any

QUALIFIED MAX REFLOW TEMPERATURE: 260°C

Device Meets MSL 1 Requirements

Use the Device Number to order the 7 inch/3,000 unit reel. Replace the "T1" with "T3" in the Device Number to order the 13 inch/10,000 unit reel.



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SOD-323 **CASE 477** STYLE 1

· Com.cr **MARKING DIAGRAM**



Specific Device Code

ZA = SD05T1

ZC = SD12T1

M = Date Code

ORDERING INFORMATION

Device	Package	Shipping [†]
SD05T1	SOD-323	3000/Tape & Reel
SD05T1G	SOD-323 (Pb-Free)	3000/Tape & Reel
SD12T1	SOD-323	3000/Tape & Reel
SD12T1G	SOD-323 (Pb-Free)	3000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Preferred devices are recommended choices for future use and best overall value.

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Power Dissipation @ 20 μ s (Note 1) @ $T_L \le 25^{\circ}C$	P _{pk}	350	Watts
IEC 61000-4-2 (ESD) Air Contact		±15 ±8.0	kV
IEC 61000-4-4 (EFT)		40	Α
ESD Voltage (Human Body Model (HBM) Waveform per IEC 61000-4-2)	V _{PP}	30	kV
Total Power Dissipation on FR–5 Board (Note 2) @ T _A = 25°C Derate above 25°C	P _D	200 1.6	mW mW/°C
Thermal Resistance Junction-to-Ambient	$R_{ hetaJA}$	635	°C/W
Junction and Storage Temperature Range	T _J , T _{stg}	-55 to +150	°C
Lead Solder Temperature - Maximum (10 Second Duration)	TL	260	°C

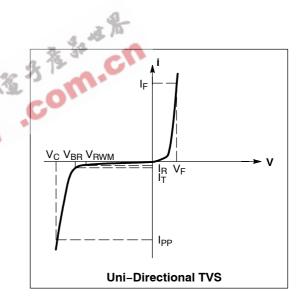
Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

- *Other voltages may be available upon request.
- 1. Nonrepetitive current pulse, per Figure 6.
- 2. $FR-5 = 1.0 \times 0.75 \times 0.62$ in.

ELECTRICAL CHARACTERISTICS

(T_A = 25°C unless otherwise noted)

Symbol	Parameter						
I _{PP}	Maximum Reverse Peak Pulse Current						
V _C	Clamping Voltage @ I _{PP}						
V_{RWM}	Working Peak Reverse Voltage						
I _R	Maximum Reverse Leakage Current @ V _{RWM}						
V_{BR}	Breakdown Voltage @ I _T						
I _T	Test Current						
I _F	Forward Current						
V _F	Forward Voltage @ I _F						

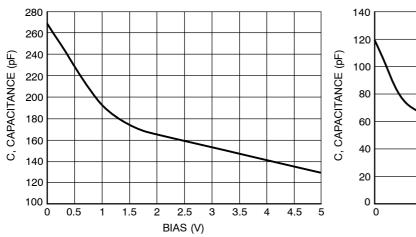


ELECTRICAL CHARACTERISTICS

			V _{BR} , Breakd	•		V _C @ I _{PP} = 5 A	Max I _{PP}	V _C @ Max I _{PP}	Max Capacitance (pF)
Device	V _{RWM} (V)	I _R @ V _{RWM} (μΑ)	Min	Max	I _T mA	(Note 3) (V)	(Note 3) (A)	(Note 3) (V)	V _R = 0 V f = 1.0 MHz
SD05T1, G	5.0	10	6.2	7.3	1.0	9.8	24	14.5	350
SD12T1, G	12	1.0	13.3	15.75	1.0	19	15	25	150

3. $8\times20~\mu s$ pulse waveform.

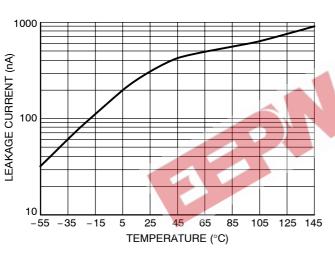
TYPICAL CHARACTERISTICS



140 120 100 80 60 40 20 0 2 4 6 8 10 12 BIAS (V)

Figure 1. SD05 Typical Capacitance versus Bias Voltage

Figure 2. SD12 Typical Capacitance versus Bias Voltage



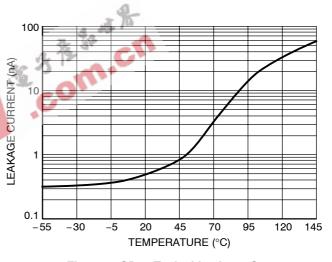
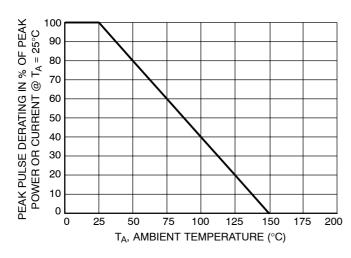


Figure 3. SD05 Typical Leakage Current versus Temperature

Figure 4. SD12 Typical Leakage Current versus Temperature



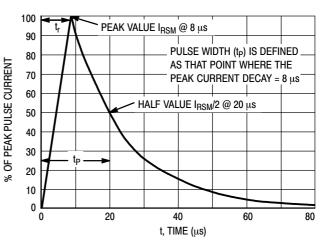
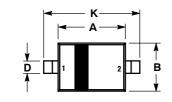


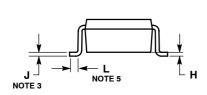
Figure 5. Pulse Derating Curve

Figure 6. 8 \times 20 μs Pulse Waveform

PACKAGE DIMENSIONS

SOD-323 CASE 477-02 ISSUE E



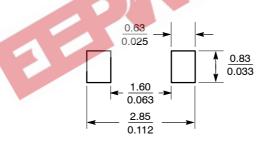




- NOTES:
 1. DIMENSIONING AND TOLERANCING PER
- ANSI Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETERS.
- LEAD THICKNESS SPECIFIED PER L/F
- LEAD THICKNESS SPECIFIED PEH (JF DRAWING WITH SOLDER PLATING. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. DIMENSION L IS MEASURED FROM END OF

	MILLIN	METERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	1.60	1.80	0.063	0.071	
В	1.15	1.35	0.045	0.053	
С	0.80	1.00	0.031	0.039	
D	0.25	0.40	0.010	0.016	
E	0.15	REF	0.006 REF		
Н	0.00	0.10	0.000	0.004	
J	0.089	0.177	0.0035	0.0070	
K	2.30	2.70	0.091	0.106	
L	0.075		0.003		

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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